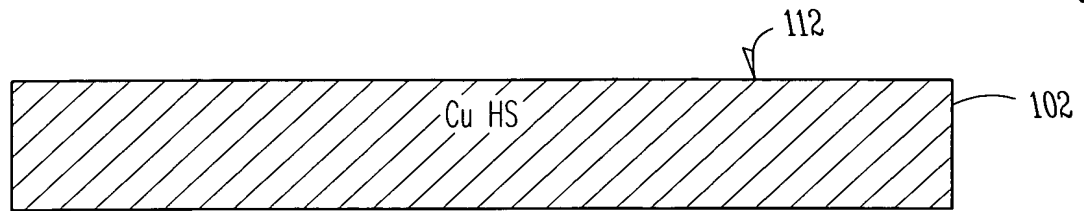


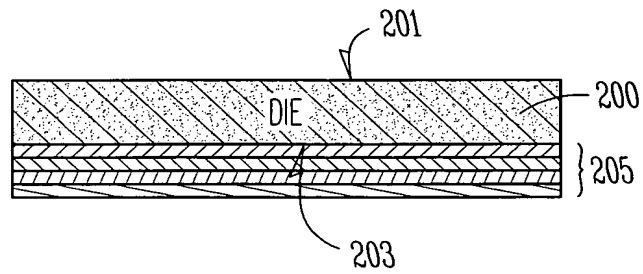


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*Fig. 1*



*Fig. 2*

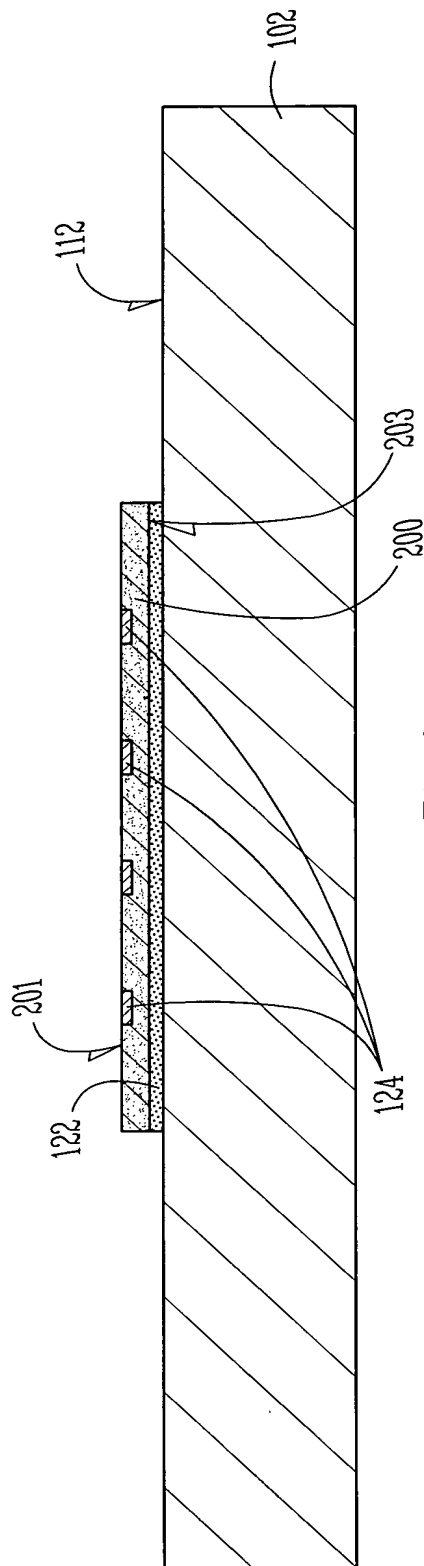


Fig. 3

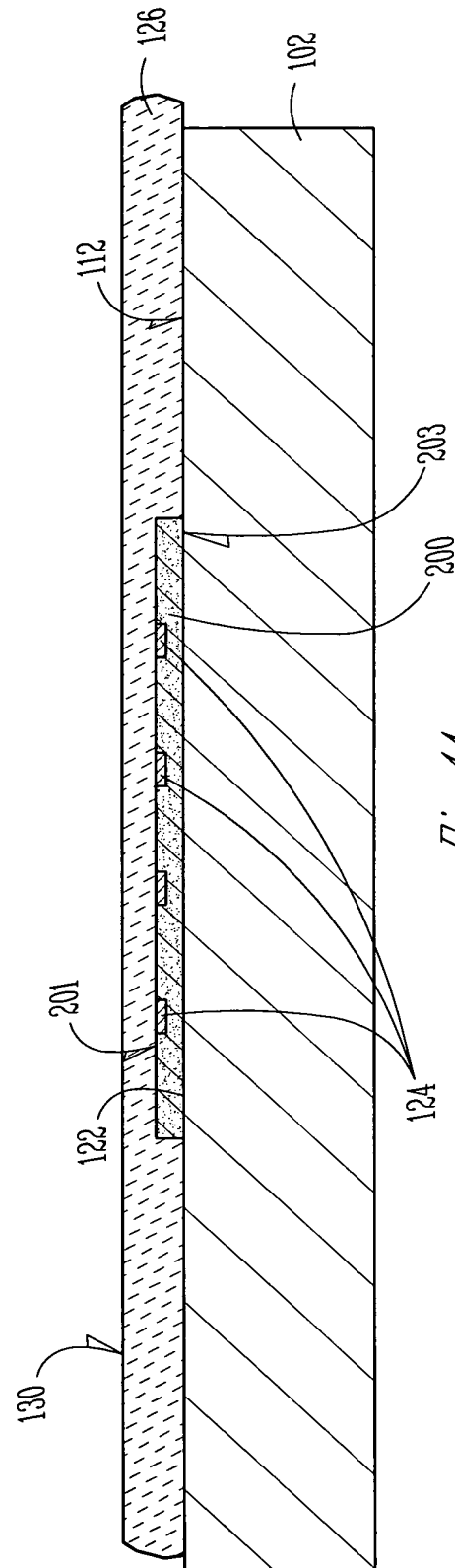
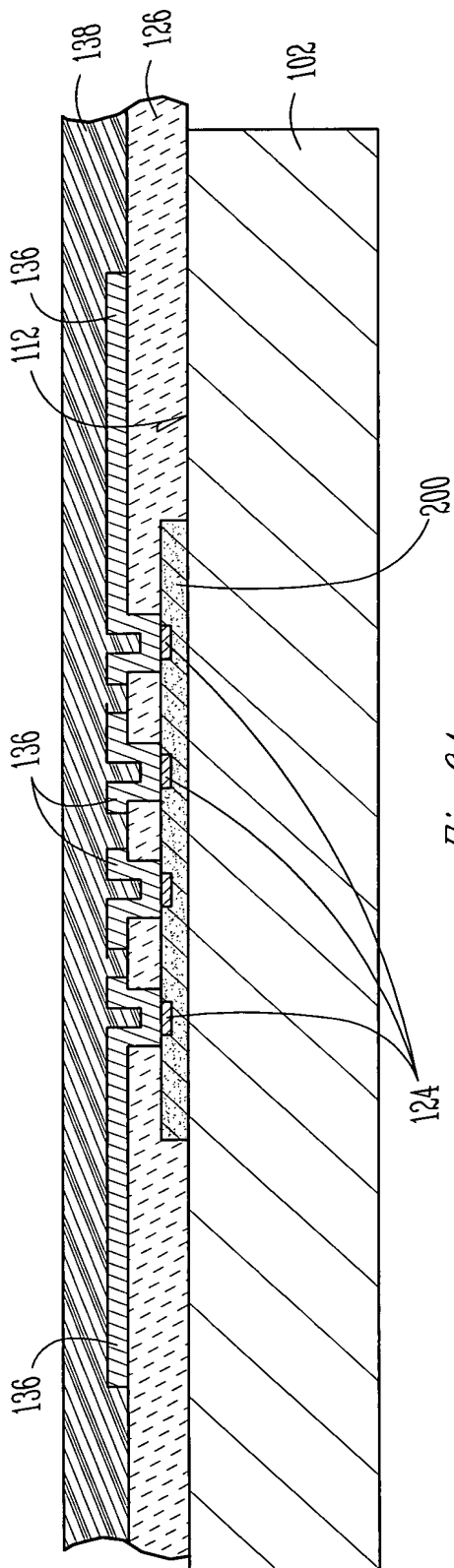
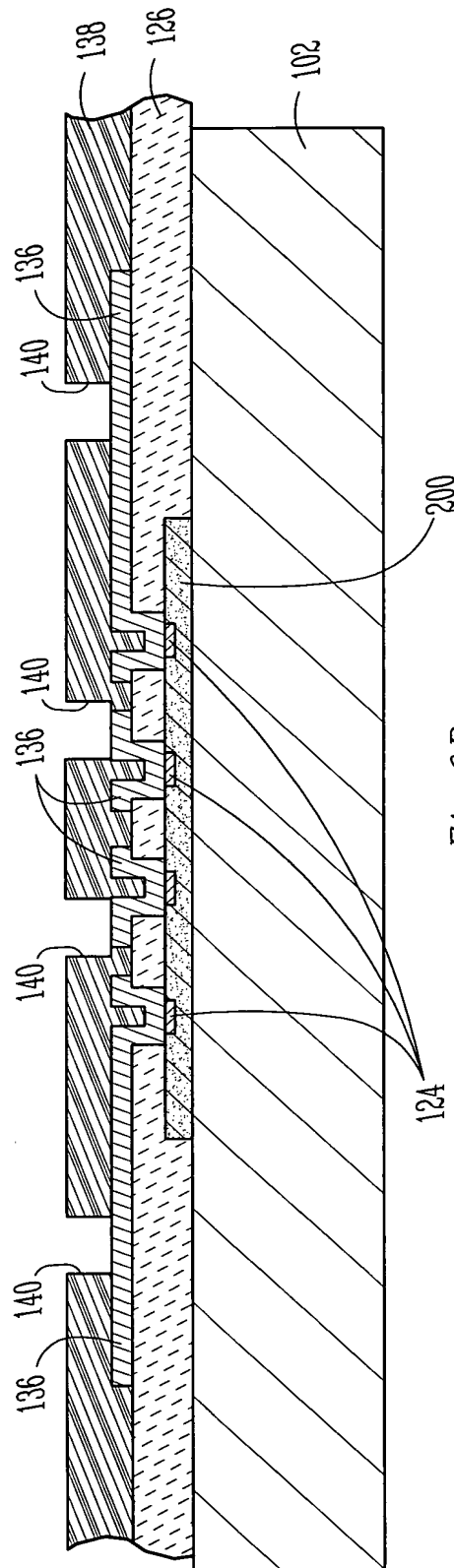


Fig. 4A

Fig. 5



*Fig. 6A*



*Fig. 6B*

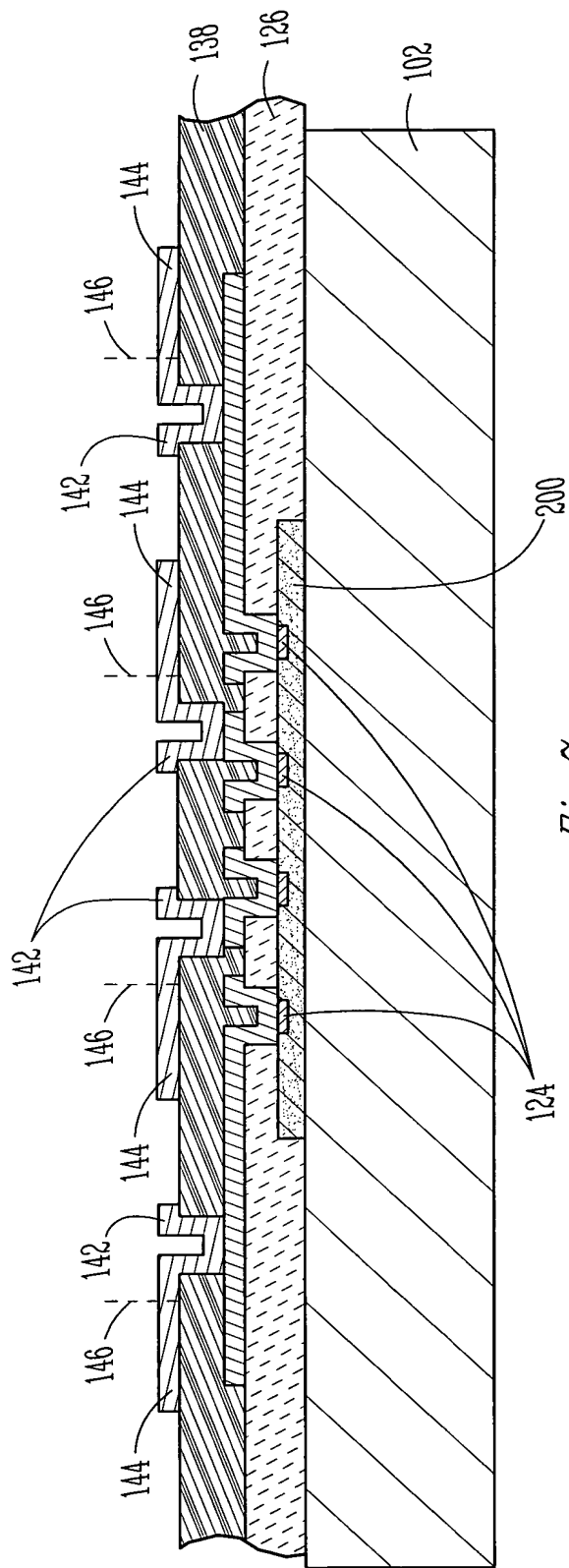


Fig. 7

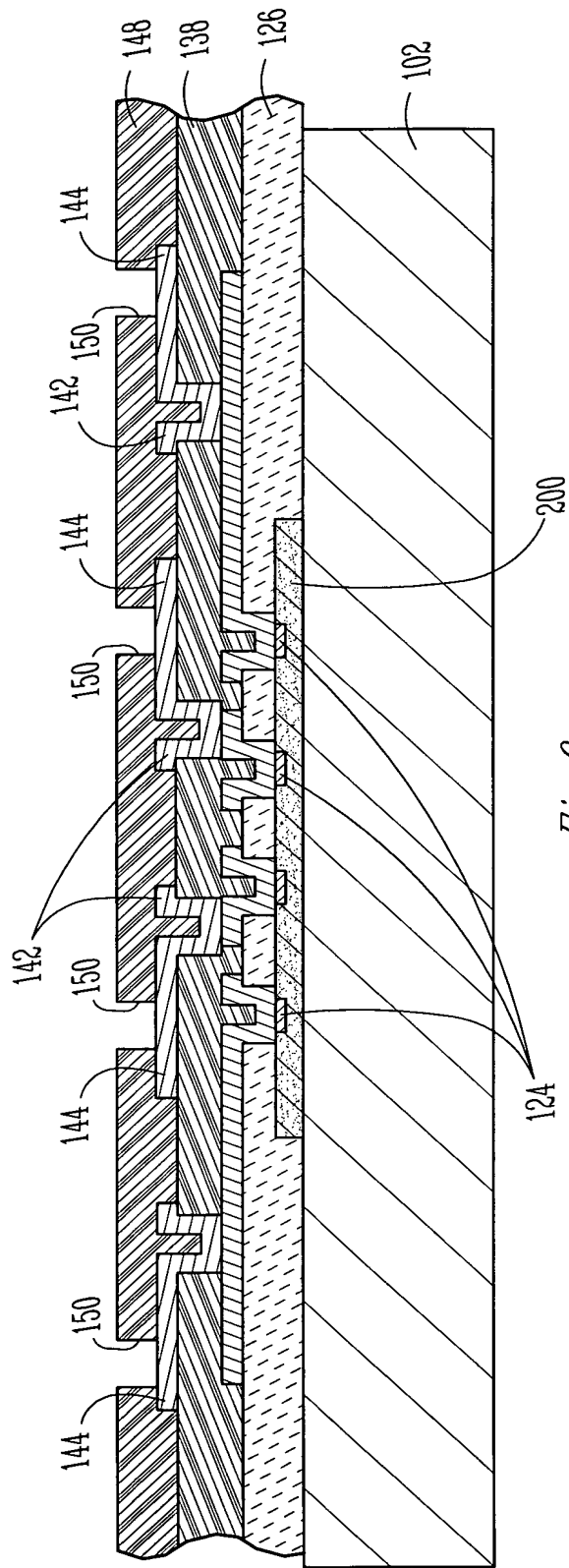


Fig. 8

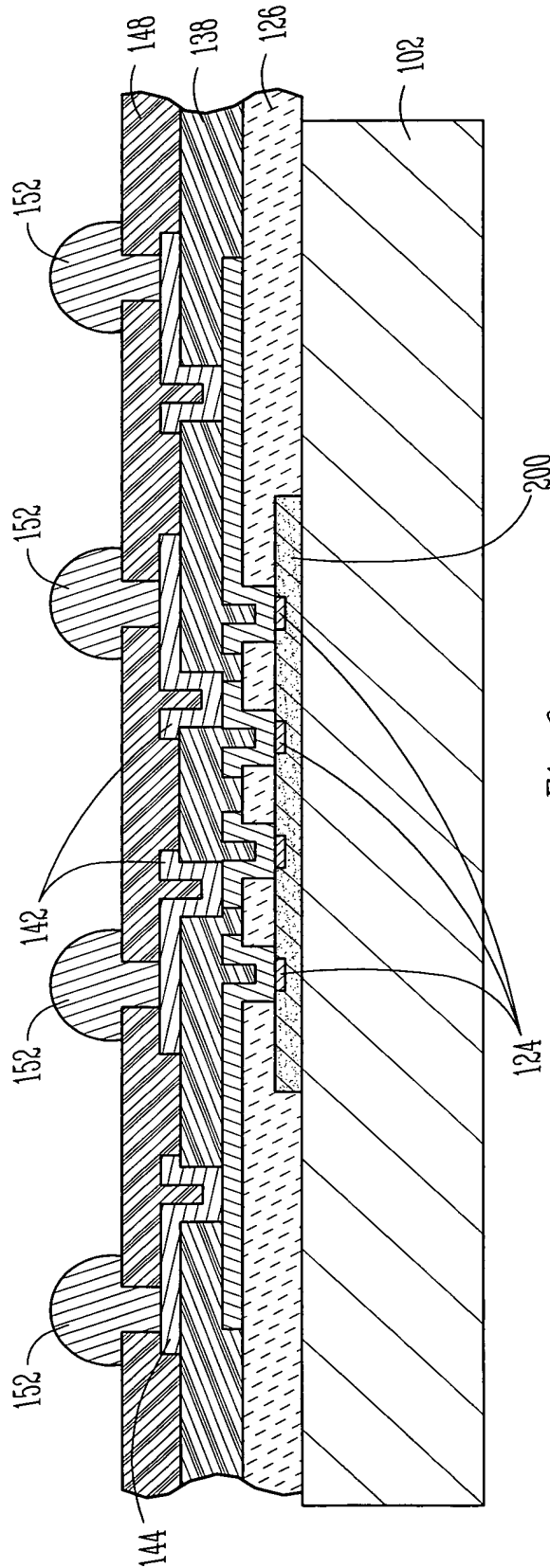
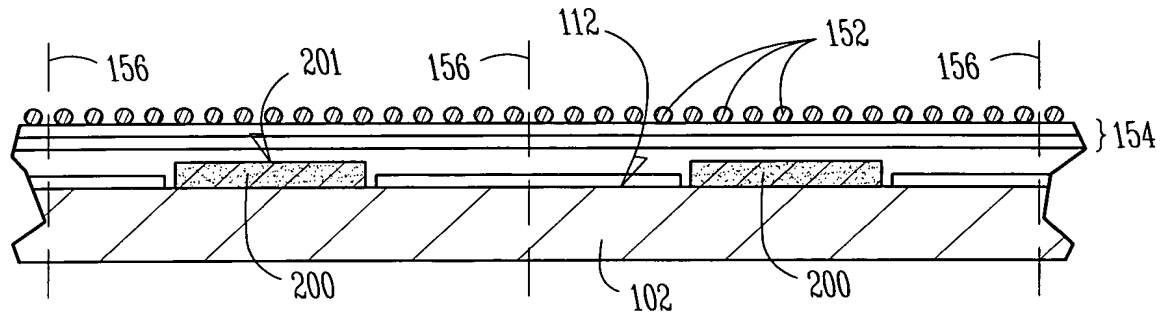


Fig. 9

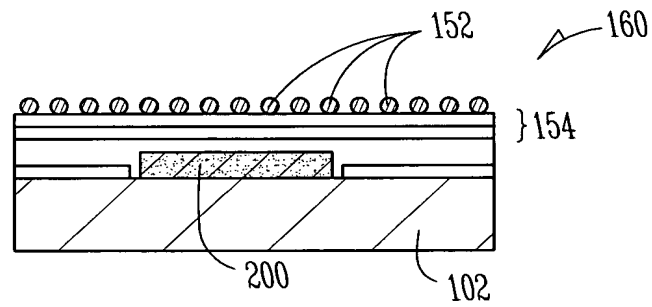


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SERIAL NO.: 10/036389

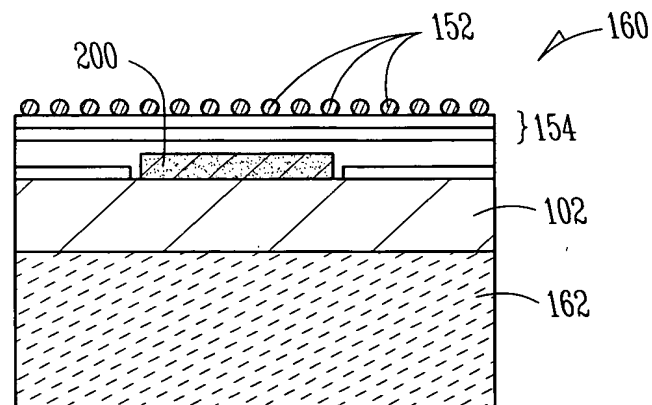
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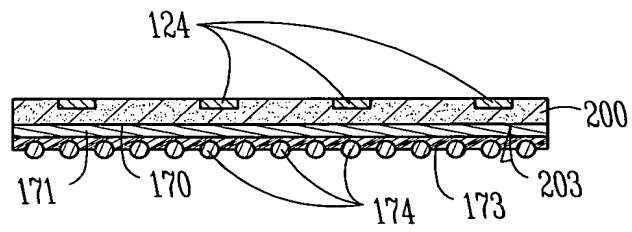
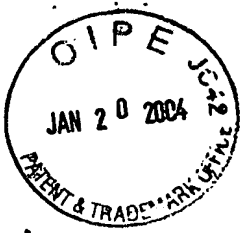
*Fig. 10A*



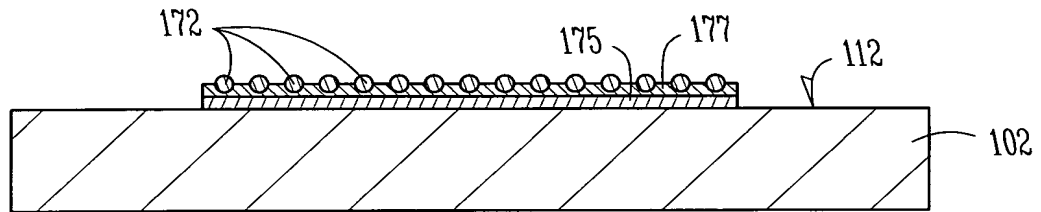
*Fig. 10B*



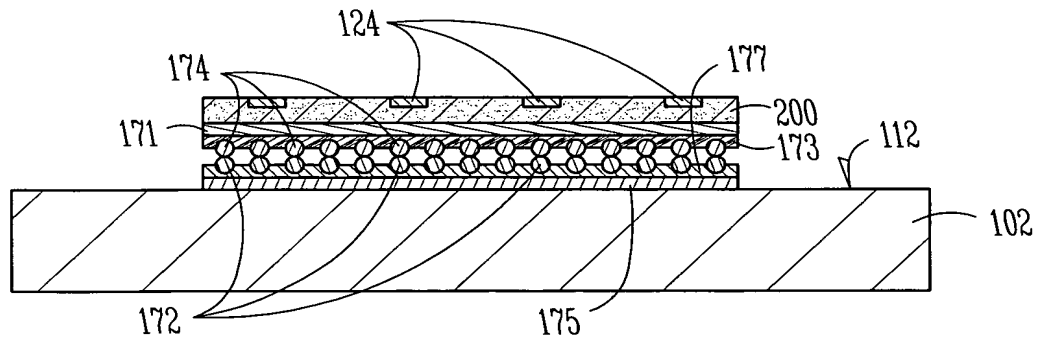
*Fig. 11*



*Fig. 12A*

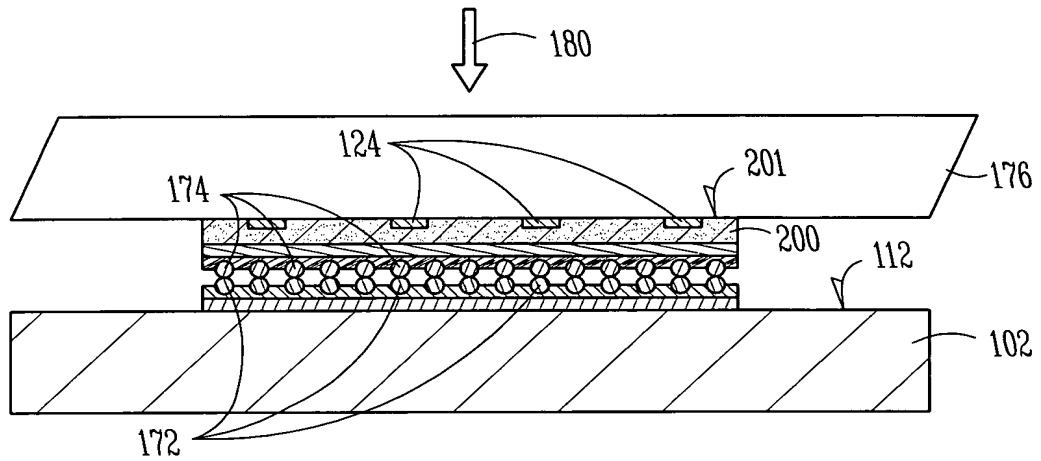


*Fig. 12B*

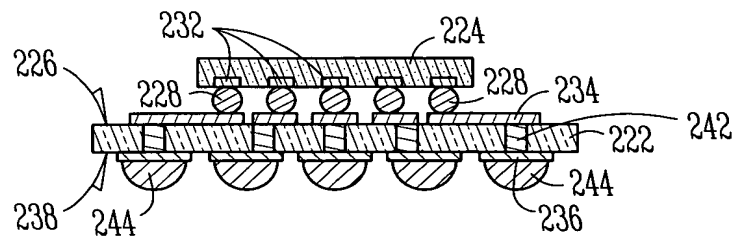


*Fig. 12C*





*Fig. 13*



*Fig. 16*  
*(Prior Art)*

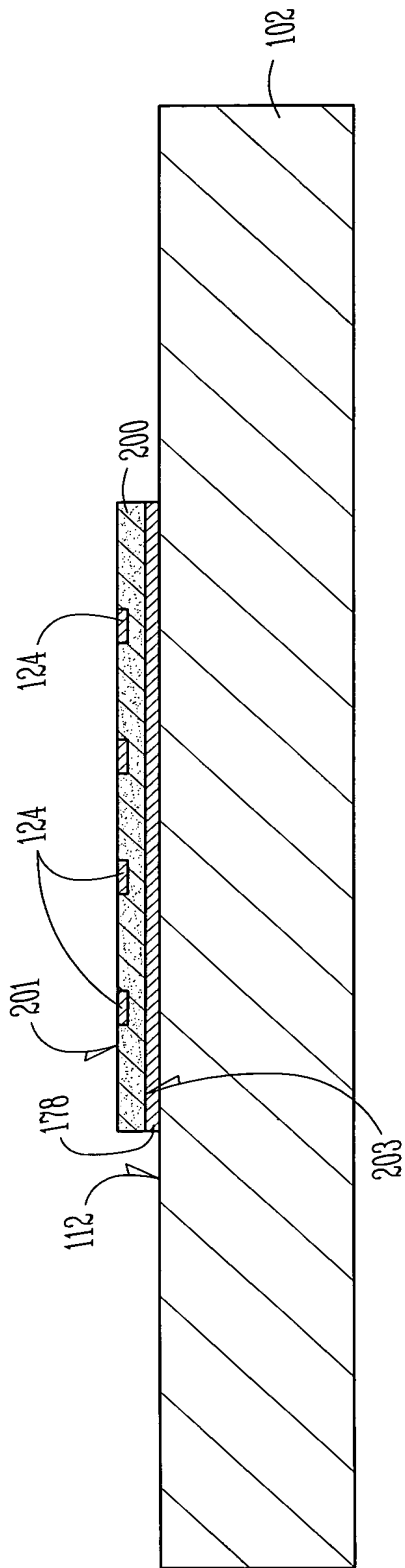


Fig. 14

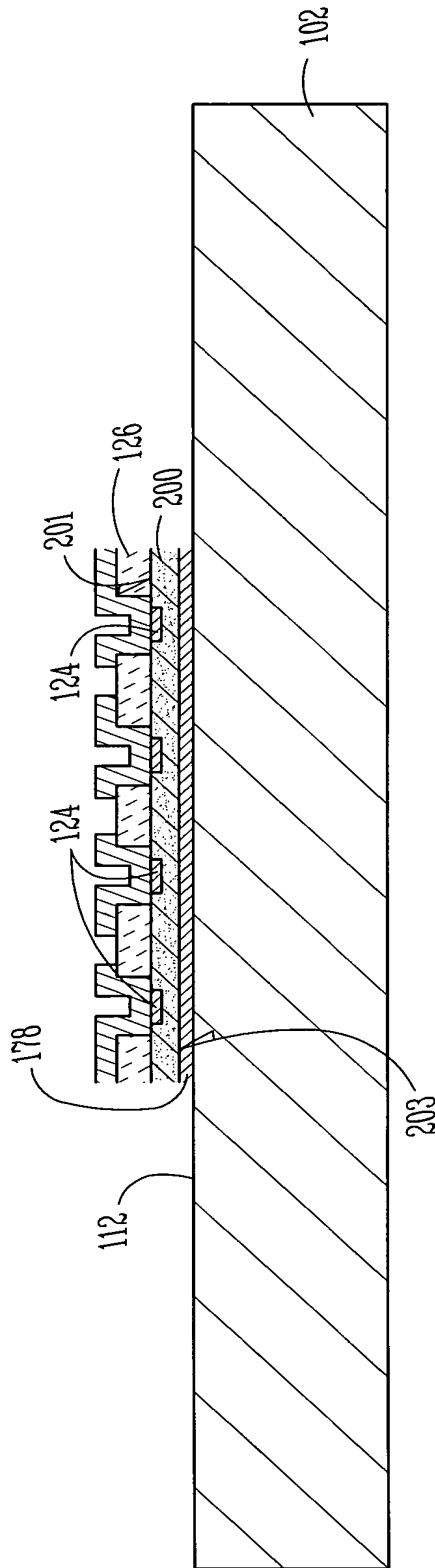


Fig. 15